

# APPLICATION DATA SHEET

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Customer Number Attorney: 31561



Customer Number Correspondence Address: 31561



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90119108

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## INVENTOR(s):

Primary Citizenship: TAIWAN

Given Name: Wen-Chih

Family Name: Yang

Residence City: Hsinchu Hsien

Residence Country: TW

Address: No. 11, Alley 2, Lane 51, Minhu Rd., Shuanghsi Tsun,  
Paoshan Hsiang

Hsinchu Hsien , TW

Primary Citizenship: TAIWAN

Given Name: Feng-Cheng

Family Name: Su

Residence City: Hsinchu Hsien

Residence Country: TW

Address: No. 11, Lane 46, Nanken Rd., Shuanghsi Tsun, Paoshan  
Hsiang

Hsinchu Hsien , TW

